Standard Recommendation
S.R. CLC/TR 62258-4:2013

Semiconductor die products -- Part 4: Questionnaire for die users and suppliers (IEC/TR 62258-4:2012 (EQV))

S.R. CLC/TR 62258-4:2013

Incorporating amendments/corrigenda issued since publication:

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TECHNICAL REPORT
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CLC/TR 62258-4

January 2013

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Supersedes CLC/TR 62258-4:2007

English version

Semiconductor die products - Part 4: Questionnaire for die users and suppliers
(IEC/TR 62258-4:2012)

Produits de puces de semiconducteurs -
Partie 4: Questionnaire destiné
aux utilisateurs et fournisseurs de puces
(CEI/TR 62258-4:2012)

Halbleiter-Chip-Erzeugnisse -
Teil 4: Fragebogen für Chip-Anwender
und -Lieferanten
(IEC/TR 62258-4:2012)

This Technical Report was approved by CENELEC on 2012-09-12.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.

CENELEC
European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

The text of document 47/2073A/DTR, future edition 2 of IEC/TR 62258-4, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as CLC/TR 62258-4:2013.

This document supersedes CLC/TR 62258-4:2007.

CLC/TR 62258-4:2013 includes the following significant technical changes with respect to CLC/TR 62258-4:2007:

The document checklist was changed to mirror EN 62258-1:2010 requirements exactly.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC [and/or CEN] shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC/TR 62258-4:2012 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC/TR 62258-7	NOTE	Harmonised as CLC/TR 62258-7.
IEC/TR 62258-8	NOTE	Harmonised as CLC/TR 62258-8.

Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

Publication	Year	Title	EN/HD	Year
IEC 60050	Series	International Electrotechnical Vocabulary (IEV)	-	-
IEC 62258-1	2009	Semiconductor die products - Part 1: Procurement and use	EN 62258-1	2010
IEC 62258-2	2011	Semiconductor die products - Part 2: Exchange data formats	EN 62258-2	2011

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DIE PRODUCTS –

Part 4: Questionnaire for die users and suppliers

FOREWORD

1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as “IEC Publication(s)”). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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The main task of IEC technical committees is to prepare International Standards. However, a technical committee may propose the publication of a technical report when it has collected data of a different kind from that which is normally published as an International Standard, for example "state of the art".

IEC 62258-4, which is a technical report, has been prepared by IEC technical committee 47: Semiconductor devices.

This technical report contains attached files in the form of 47-62258-4-TR-E-worksheet.xls. These files are intended to be used as a complement and do not form an integral part of the technical report.

This second edition cancels and replaces the first edition published in 2007 and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

The document checklist was changed to mirror IEC 62258-1:2009 requirements exactly.

The text of this technical report is based on the following documents:

Enquiry draft	Report on voting
47/2073A/DTR	47/2108/RVC

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 62258 series, published under the general title *Semiconductor die products*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

INTRODUCTION

This technical report is based on the work carried out in the ESPRIT 4th Framework Project GOODDIE which resulted in the publication of the ES 59008 series of European specifications. Organizations that helped prepare this document included the ESPRIT ENCAST and ENCASIT projects, the Die Products Consortium, JEITA, JEDEC and ZVEI.

SEMICONDUCTOR DIE PRODUCTS –

Part 4: Questionnaire for die users and suppliers

1 Scope

This part of IEC 62258 has been developed to facilitate the production, supply and use of semiconductor die products, including:

- wafers;
- singulated bare die;
- die and wafers with attached connection structures;
- minimally or partially encapsulated die and wafers.

This technical report contains a questionnaire, based on the requirements of other parts of IEC 62258, which may be used in negotiations and contracts between suppliers and purchasers of die devices. It is intended to assist all those involved in the supply chain for die devices to comply with the requirements of the IEC 62258-1:2009 and IEC 62258-2:2011 standards.

It should be recognized that the tables contained in this technical report form a checklist of information that can potentially be supplied and that it may not be relevant or possible to complete all fields. Different markets may require different subsets of the information requested herein.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050 (all parts), *International Electrotechnical Vocabulary* (available at http://www.electropedia.org)

IEC 62258-1:2009, *Semiconductor die products – Part 1: Procurement and use*

IEC 62258-2:2011 *Semiconductor die products – Part 2: Exchange data formats*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in the IEC 60050 series and IEC 62258-2:2011 apply.

4 General

To comply with IEC 62258-1:2009, that standard requires that suppliers of die devices furnish information which is necessary and sufficient for users of the devices at all stages of design, procurement, manufacture and test of the products containing them. The questionnaire in Annex A provides a *pro forma* that can form a standard basis for supplying such information and is intended as an aid to compliance with the standard.